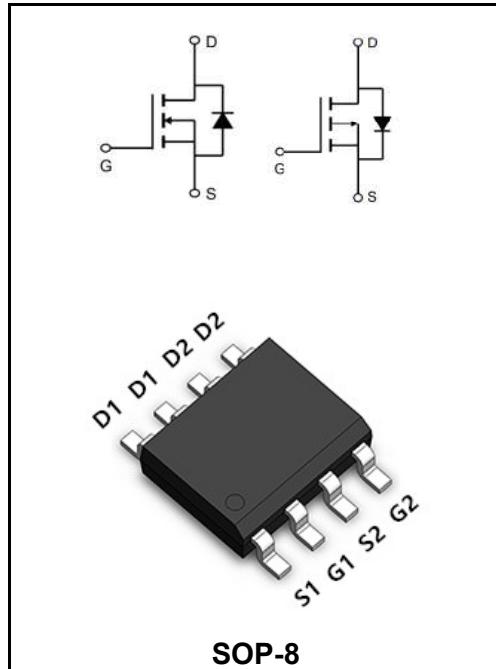


**60V N+P-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	12.5A
$V_{DSS}$	60V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 36mΩ (Type: 28 mΩ)
$I_D$	-9.7A
$V_{DSS}$	-60V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 70mΩ (Type: 48 mΩ)


**Application**

- ↳ Boost driver
- ↳ Brushless motor

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW10G06S	SOP-8	YFW 10G06S XXXXX	3000PCS/Tape

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbols	Value		Units
		N-Ch	P-Ch	
Drain-Source Voltage	$V_{DS}$	60	-60	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_A=25^\circ\text{C}$	$I_D$	12.5	-9.7	A
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_A=70^\circ\text{C}$	$I_D$	5.8	-5	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	37.5	22.5	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	25.5	35.3	mJ
Avalanche Current	$I_{AS}$	22.6	-26.6	A
Total Power Dissipation <sup>4</sup> @ $T_A=25^\circ\text{C}$	$P_D$	1.5	1.5	W
Storage Temperature Range	$T_{STG}$	-55 to +150		°C
Operating Junction Temperature Range	$T_J$	-55 to +150		°C

**N-Channel Electrical Characteristics (TJ=25 °C, unless otherwise noted)**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	BV <sub>DSS</sub>	60	66	-	V
BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	ΔBV <sub>DSS/ΔTJ</sub>	-	0.063	-	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =4A	R <sub>DS(ON)</sub>	-	28	36	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A		-	32	38	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	V <sub>GS(th)</sub>	1.2	1.6	2.5	V
V <sub>GS(th)</sub> Temperature Coefficient		ΔV <sub>GS(th)</sub>	-	-5.24	-	mV/°C
Drain-Source Leakage Current	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	uA
	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	5	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> = 5V, I <sub>D</sub> = 4A	g <sub>f</sub>	-	21	-	S
Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	R <sub>g</sub>		3.2		Ω
Total Gate Charge(4.5V)	V <sub>DS</sub> =48V V <sub>GS</sub> =4.5V I <sub>D</sub> =4A	Q <sub>g</sub>	-	12.6	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	3.2	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	6.3	-	
Turn-on delay time	V <sub>DD</sub> =30V V <sub>GS</sub> =10V R <sub>G</sub> = 3.3 I <sub>D</sub> = 4A	t <sub>d(on)</sub>	-	8	-	ns
Rise Time		T <sub>r</sub>	-	14.2	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	24.4	-	
Fall Time		t <sub>f</sub>	-	4.6	-	
Input Capacitance	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1MHz	C <sub>iss</sub>	-	1378	-	pF
Output Capacitance		C <sub>oss</sub>	-	86	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	64	-	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	4.8	A
Pulsed Source Current <sup>2,5</sup>		I <sub>SM</sub>	-	-	9.6	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	1.2	V

Note :

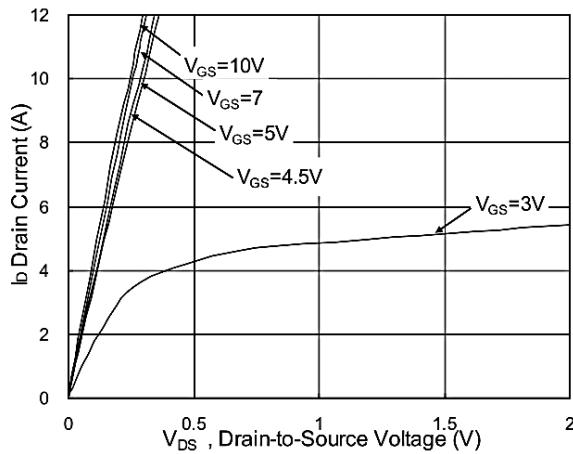
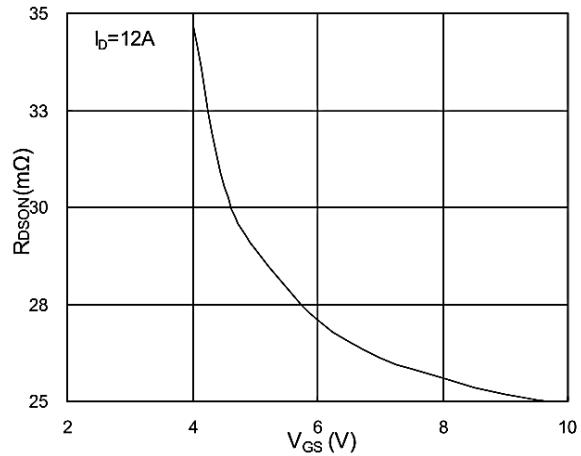
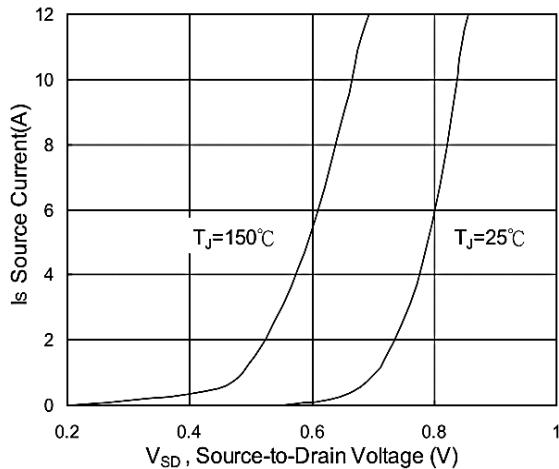
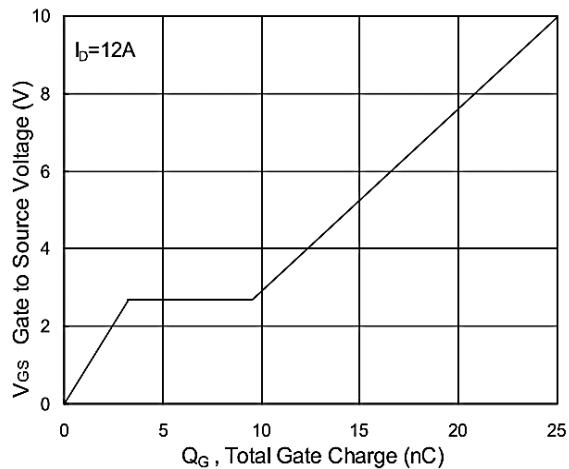
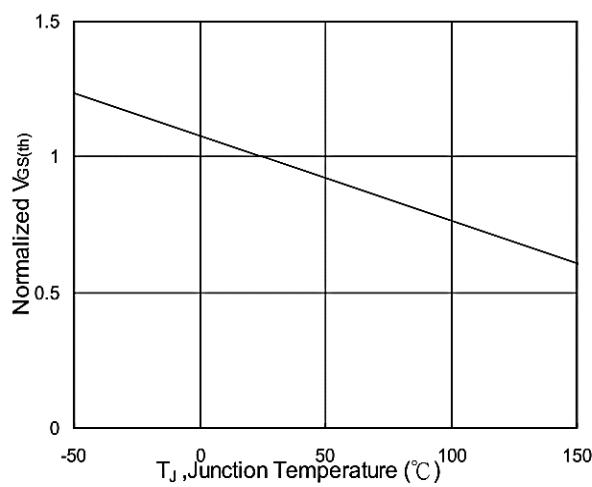
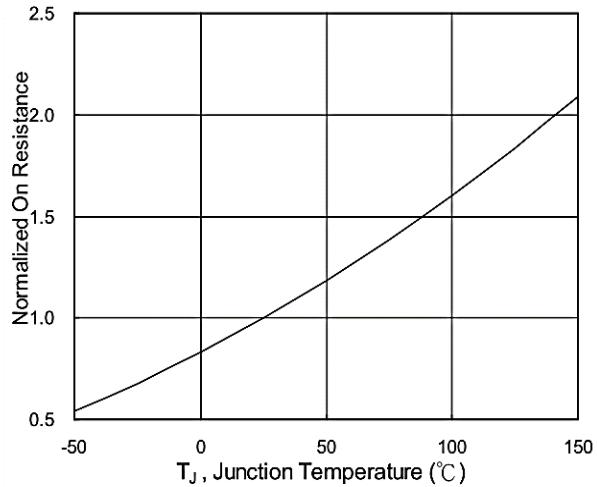
- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation

**P-Channel Electrical Characteristics (TJ=25 °C, unless otherwise noted)**

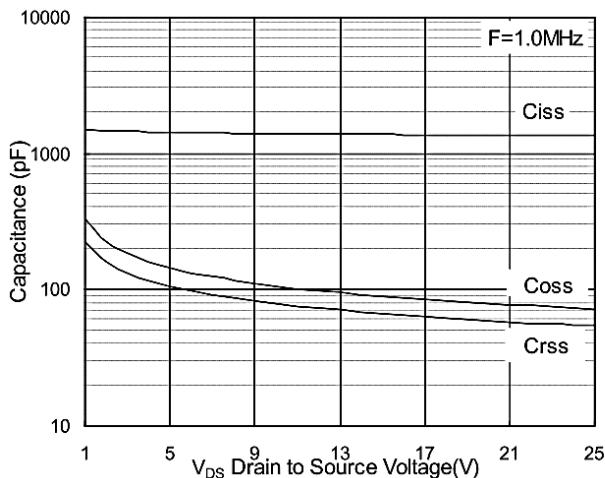
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	$BV_{DSS}$	-60	-	-	<b>V</b>
BVDSS Temperature Coefficient	Reference to 25°C , $I_D=-1mA$	$\Delta BV_{DSS/\Delta TJ}$	-	-0.03	-	<b>V/°C</b>
Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10V, I_D=-3A$	$R_{DS(ON)}$	-	48	70	<b>mΩ</b>
	$V_{GS}=-4.5V, I_D=-2A$		-	75	85	
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	$V_{GS(th)}$	-1.2	-1.6	-2.5	<b>V</b>
$V_{GS(th)}$ Temperature Coefficient		$\Delta V_{GS(th)}$	-	4.56	-	<b>mV/°C</b>
Drain-Source Leakage Current	$V_{DS}=-48V, V_{GS}=0V, T_J=25^{\circ}C$	$I_{DSS}$	-	-	1	<b>uA</b>
	$V_{DS}=-48V, V_{GS}=0V, T_J=55^{\circ}C$		-	-	5	
Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	$I_{GS}$	-	-	$\pm 100$	<b>nA</b>
Forward Transconductance	$V_{DS}=-5V, I_D = -3A$	$g_{fs}$	-	15	-	<b>S</b>
Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	$R_g$		13.5	-	<b>Ω</b>
Total Gate Charge(-4.5V)	$V_{DS}=-48V$ $V_{GS}=-4.5V$ $I_D=-3A$	$Q_g$	-	9.86	-	<b>nC</b>
Gate-Source Charge		$Q_{gs}$	-	3.1	-	
Gate-Drain Charge		$Q_{gd}$	-	2.95	-	
Turn-on delay time	$V_{DD}=-15V$ $V_{GS}=-10V$ $R_G = 3.3$ $I_D=-1A$	$t_{d(on)}$	-	28.8	-	<b>ns</b>
Rise Time		$T_r$	-	19.8	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	60.8	-	
Fall Time		$t_f$	-	7.2	-	
Input Capacitance	$V_{DS}=-15V$ $V_{GS}=0V$ $f=1MHz$	$C_{iss}$	-	1447	-	<b>pF</b>
Output Capacitance		$C_{oss}$	-	97.3	-	
Reverse Transfer Capacitance		$C_{rss}$	-	70	-	
Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	$I_s$	-	-	-3.7	<b>A</b>
Pulsed Source Current <sup>2,5</sup>		$I_{SM}$	-	-	-7.5	<b>A</b>
Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_s=-1A, T_J=25^{\circ}C$	$V_{SD}$	-	-	-1.2	<b>V</b>

Note :

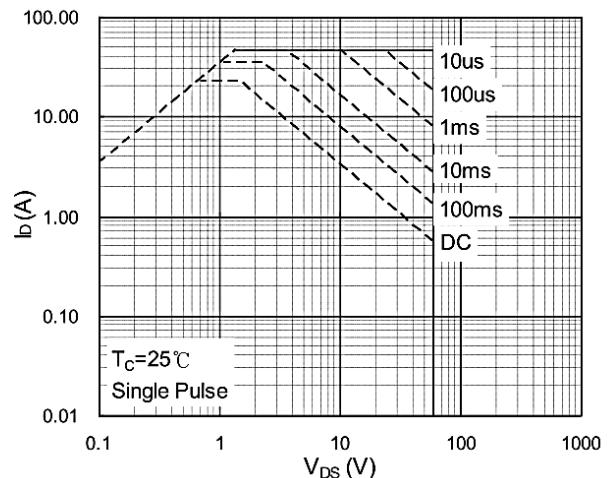
1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**Ratings and Characteristic Curves**
**N-Channel Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance v.s Gate-Source**

**Fig.3 Forward Characteristics of Reverse**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

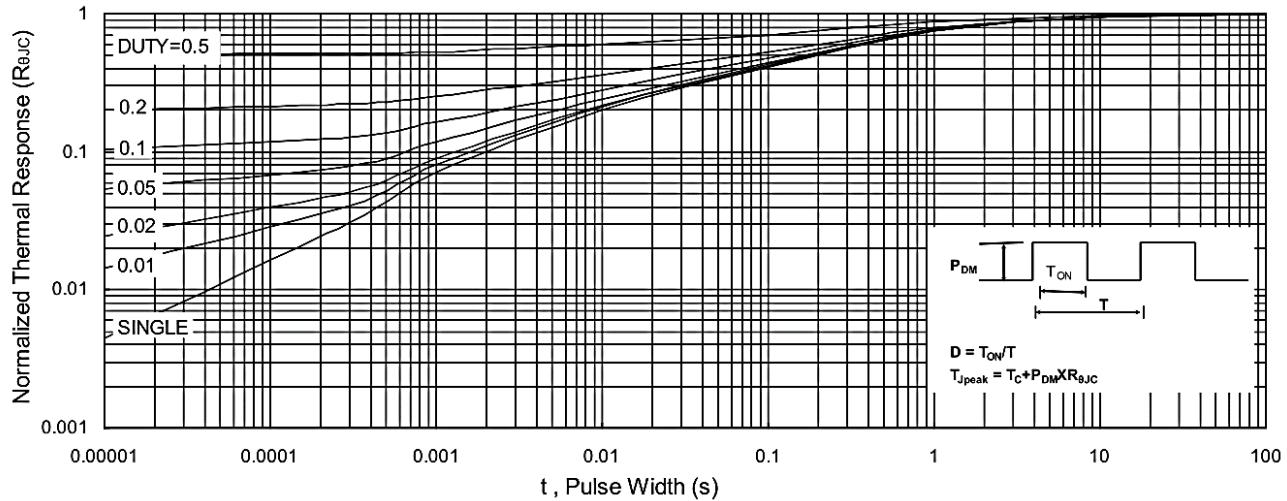
**Ratings and Characteristic Curves**



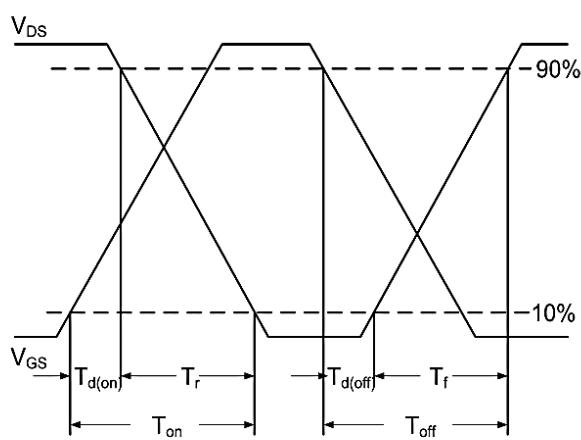
**Fig.7 Capacitance**



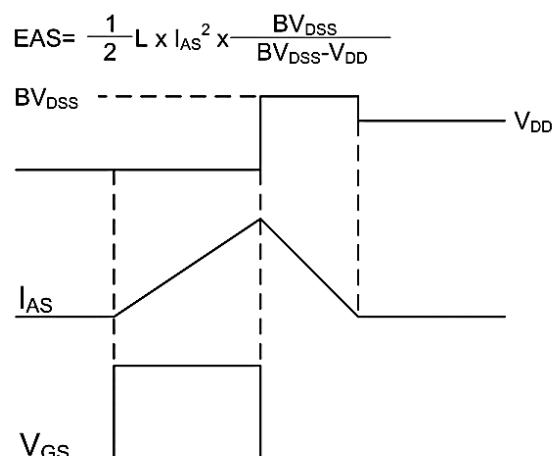
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



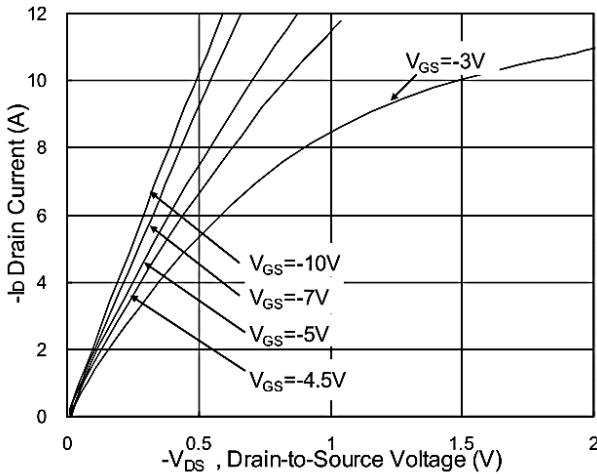
**Fig.10 Switching Time Waveform**



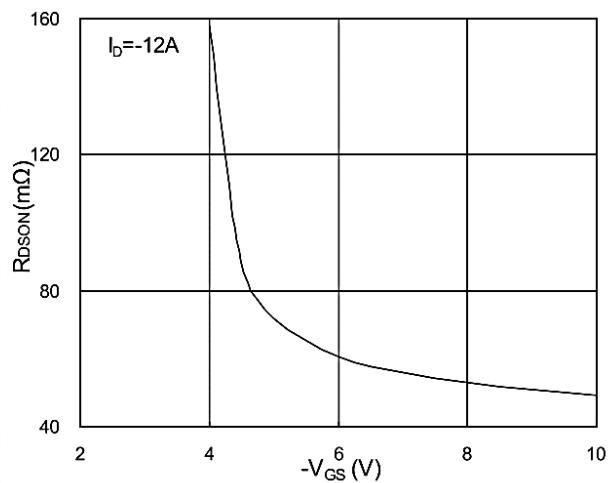
**Fig.11 Unclamped Inductive Waveform**

**Ratings and Characteristic Curves**

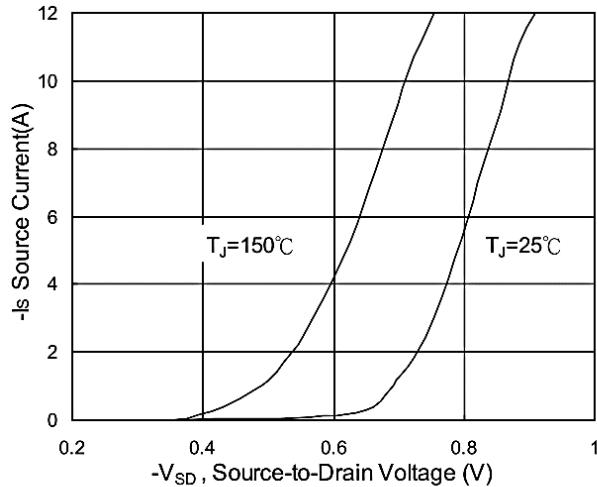
**P-Channel Typical Characteristics**



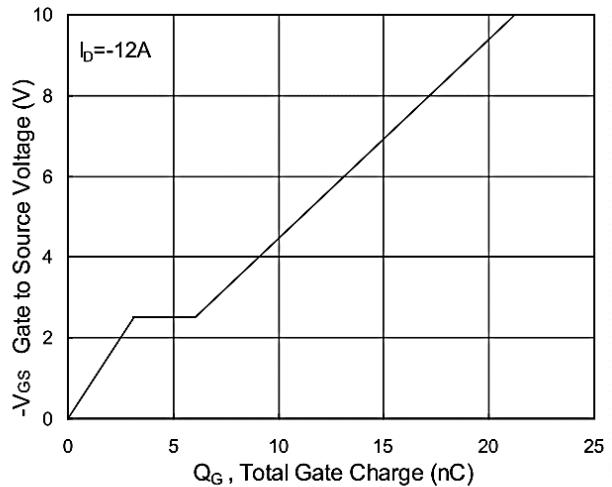
**Fig.1 Typical Output Characteristics**



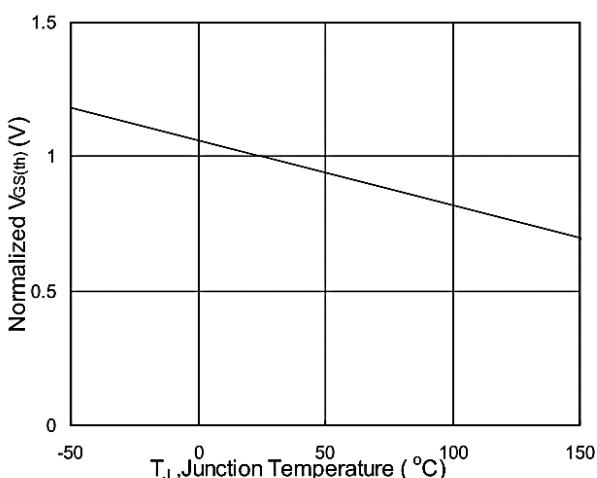
**Fig.2 On-Resistance v.s Gate-Source**



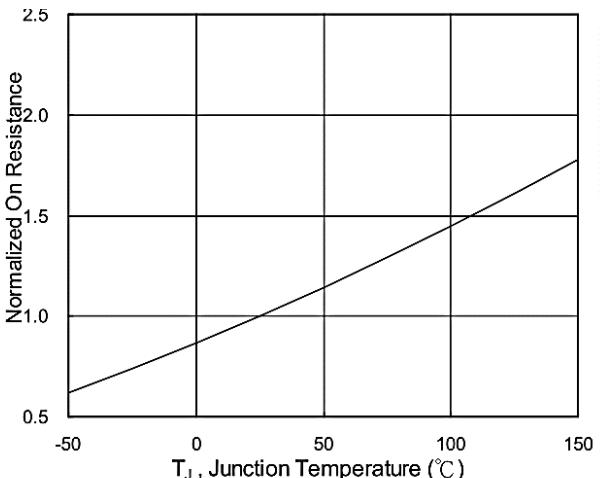
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**



**Fig.6 Normalized  $R_{DSON}$  v.s  $T_J$**

**Ratings and Characteristic Curves**

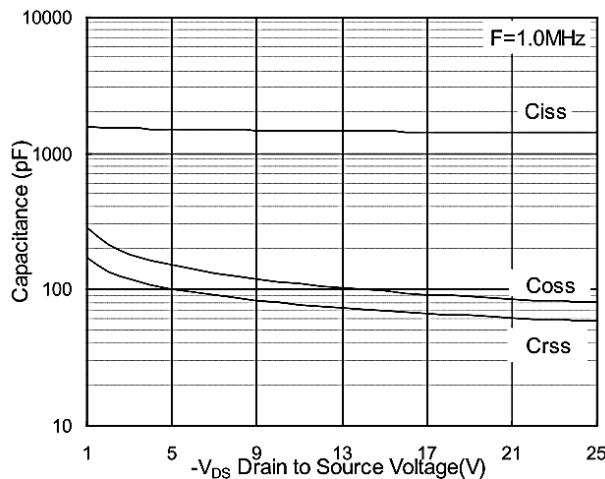


Fig.7 Capacitance

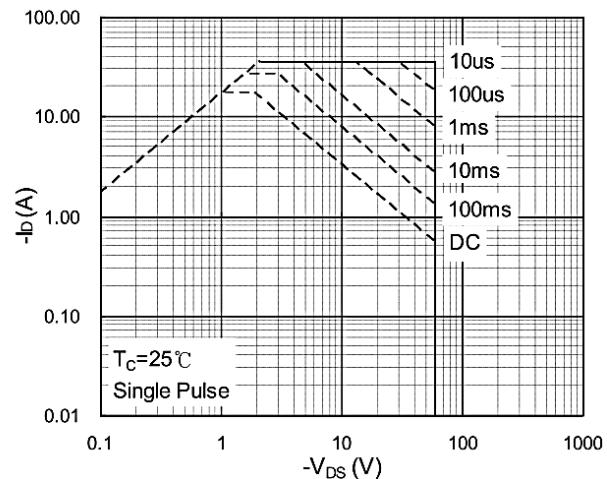


Fig.8 Safe Operating Area

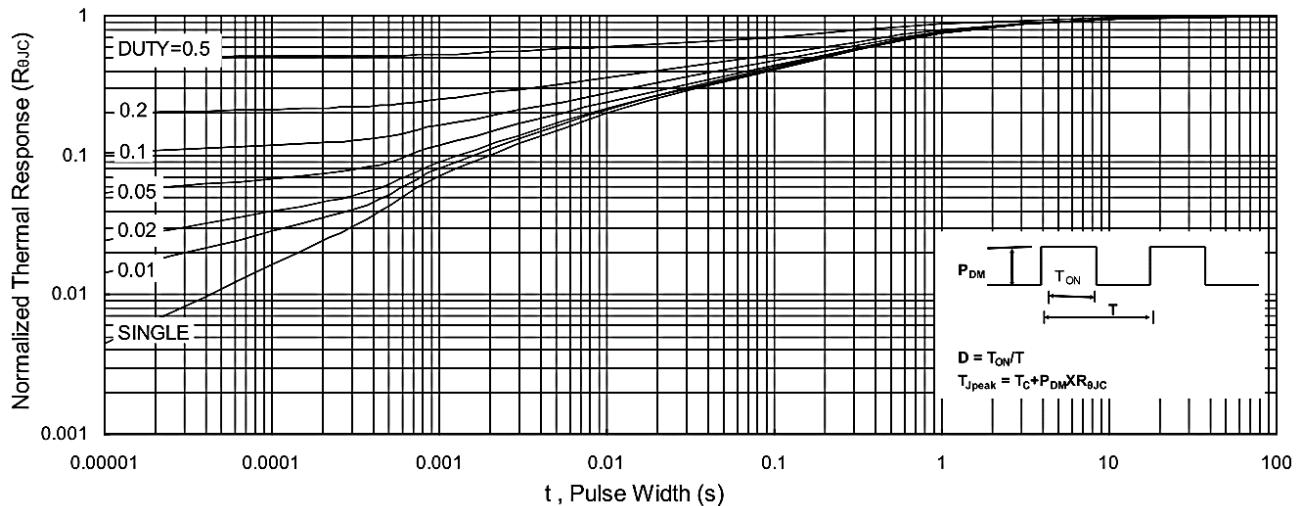


Fig.9 Normalized Maximum Transient Thermal Impedance

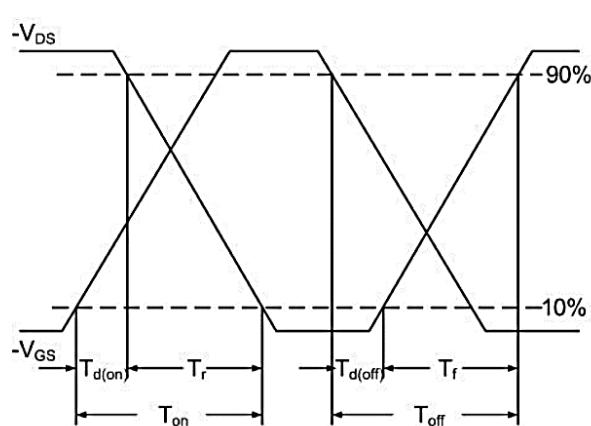


Fig.10 Switching Time Waveform

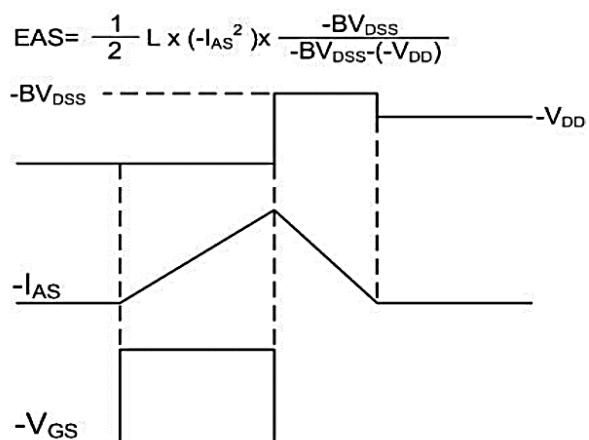
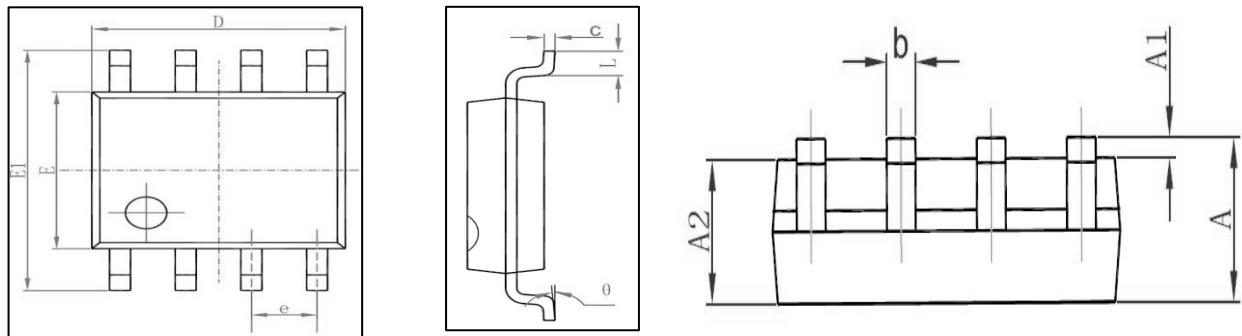


Fig.11 Unclamped Inductive Waveform

**Package Outline Dimensions Millimeters**
**SOP-8**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

